

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7509186

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHEOL MIN YUN	08/22/2022
HYE JIN PARK	08/22/2022
RECEIVING PARTY DATA	
Name:	SK INNOVATION CO., LTD.
Street Address:	26, JONG-RO, JONGNO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	03188
Name:	SK IE TECHNOLOGY CO., LTD.
Street Address:	26, JONG-RO, JONGNO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	03188
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17897365
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	05038-2205618
NAME OF SUBMITTER:	RICHARD L BYRNE, REG. NO 28,498
SIGNATURE:	/Richard L. Byrne/

DATE SIGNED:	08/29/2022
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

ASSIGNMENT

WHEREAS, as a below named inventor, I have invented certain new and useful improvements in

METHOD OF PREPARING COMPOSITION FOR FORMING POLYIMIDE FILM,
COMPOSITION FOR FORMING POLYIMIDE FILM PREPARED THEREFROM, AND
USE THEREOF

(Invention Title)

☒ for which I have this day executed an application for a United States Patent (hereinafter "said application").

AND/OR

☐ for which an application for a United States Patent was filed on _____ (mm/dd/yyyy) and bears Application Number _____ (hereinafter "said application").

AND/OR

☐ for which an international patent application was filed under the Patent Cooperation Treaty on _____ (mm/dd/yyyy), bearing Application No. _____ (hereinafter "said application").

AND, WHEREAS, SK Innovation Co., Ltd., a corporation of Republic of Korea, having a place of business at 26, Jong-ro, Jongno-gu, Seoul 03188, Republic of Korea, and

SK ie technology Co., Ltd., a corporation of Republic of Korea, having a place of business at 26, Jong-ro, Jongno-gu, Seoul 03188, Republic of Korea, hereinafter called the "assignees", are desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to me by said assignees, the receipt of which is hereby acknowledged, I as the inventor or as one of the inventors, hereinafter the assignor(s), do hereby assign, sell and transfer unto said assignees the full and exclusive right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries, including rights of priority under the International Convention of Paris (1883) as amended, and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals and/or extensions thereof. Such assignment extends to the full ends of the terms of these applications and patents as fully and entirely as the same would have been held and enjoyed by me had this Assignment not been made.

I hereby authorize and request any attorney associated with The Webb Law Firm, Customer No. 28289, to insert here in parentheses (Application No. 17/897,365, filed 08/29/2022) the filing date and application number of said application when known.

I covenant that I am the lawful owner(s) of said application, inventions and improvements, that the same are unencumbered, that no license has been granted to make, use or vend the said inventions or improvements or any of them, and that I have the full right to make this Assignment.

And for the consideration aforesaid, I agree individually and, if applicable, jointly that I will communicate to said assignees or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts deemed necessary or expedient by said assignees or by counsel for said assignees to assist or enable said assignees to obtain and enforce full benefits from the rights and interests herein assigned. This Assignment shall be binding upon my heirs, executors, administrators and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns, as the case may be, of said assignees.

1. FULL NAME OF ASSIGNOR:

Cheol Min Yun

RESIDENCE:

Daejeon, Republic of Korea

EXECUTED this 22 day of Aug, 2022

[Signature]
SIGNATURE

WITNESS:

2. FULL NAME OF ASSIGNOR:

Hye Jin Park

RESIDENCE:

Daejeon, Republic of Korea

EXECUTED this 22 day of Aug, 2022

[Signature]
SIGNATURE

WITNESS:

☐ Checked Box indicates ____ additional page(s) for inventor signatures.